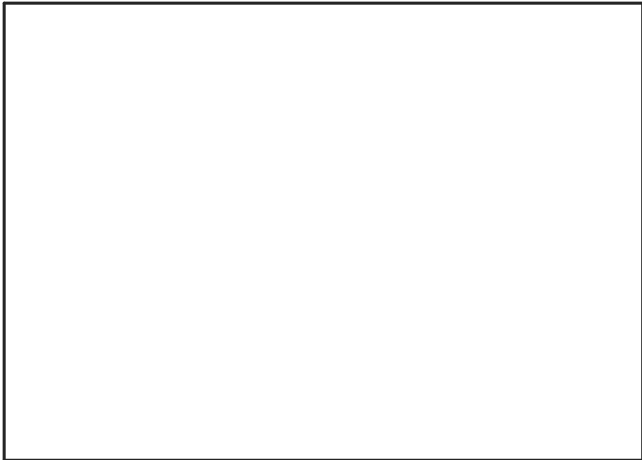


TABLE 1

Variant	Label text
001	ChangeMe!
002	ChangeMe!

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP9073	REV: A	SVN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 8/5/2013	3:03:34 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP9073	REV: A	SVN REV: Not In VersionControl
	IGNORE -> Bottom Overlay		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/5/2013 3:03:35 PM	TEXAS INSTRUMENTS	

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